

Panel 1 Speakers

Advances and Challenges in Metrology and Test for Heterogeneous Integration



Dr Choon Beng Sia

Technical Director, FormFactor Singapore



James Stephen Papanu

Senior Director, Tokyo Electron Limited (TEL)



Dr Bhupi Kumar

Advanced Packaging Technical Director, KLA



Moderator:

Pax Wang

Technology Development Director, UMC

Panel 2 Speakers

Co-Packaged Optics: The Next Inflection Point for Advanced Packaging



Dr. Torsten Wipiejewski

Technical Advisor of Huawei's European Research Institute



Cindy Palar

GM, Celestial AI Singapore



Jagadish CV

CEO of Advanced Micro Foundry



Moderator:

Dr. Surya Bhattacharya

Director, Institute of Microelectronics (IME), A*STAR
